



Rudolph Sonus 7800

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Rudolph Technologies has introduced the SONUS Technology for measuring thick films and film stacks used in copper pillar bumps and for detecting defects, such as voids, in through silicon vias (TSVs). Copper pillar bumps are a critical component of many advanced packaging technologies and TSVs provide a means for signals to pass through multiple vertically stacked chips in three dimensional integrated circuits (3DIC). The SONUS Technology is non-contact and nondestructive, and is designed to provide faster, less costly measurements and greater sensitivity to smaller defects than existing alternatives such as X-ray tomography and acoustic microscopy.





